

Maximum Ratings (@T_A = +25°C, unless otherwise specified.), Per Element

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	2700	W	8/20μs, Per Figure 1
Peak Pulse Current	I _{PP}	24	A	8/20μs, Per Figure 1
ESD Protection – Contact Discharge	V _{ESD_Contact}	±30	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V _{ESD_Air}	±30	kV	IEC 61000-4-2 Standard

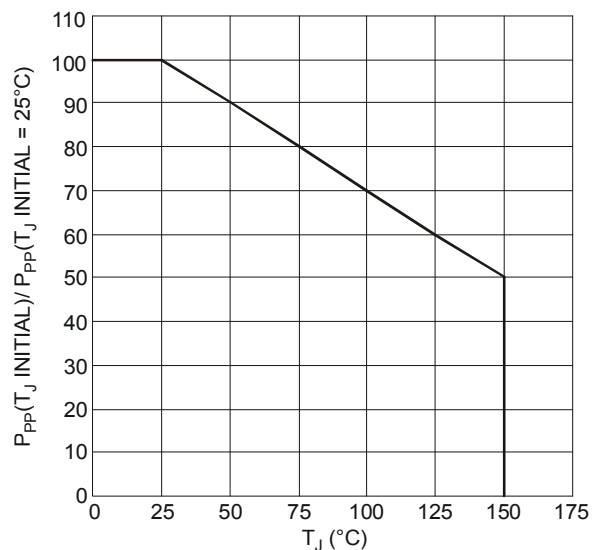
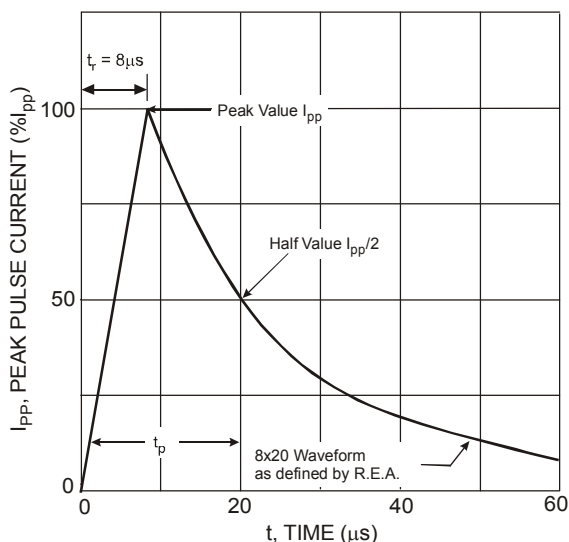
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	125	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	58	V	—
Channel Leakage Current (Note 6)	I _{RM}	—	—	0.2	μA	V _{RWM} = 58V
Breakdown Voltage	V _{BR}	64.4	—	71.2	V	I _R = 1mA
Clamping Voltage	V _{CL}	—	—	100	V	I _{PP} = 24A, t _p = 8/20μs
Channel Input Capacitance	C _T	—	55	—	pF	V _R = 50V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.



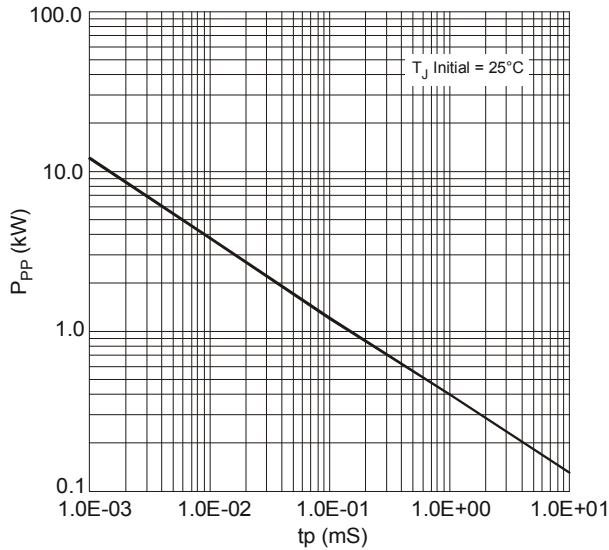


Figure 3 Peak Pulse Power vs. Exponential Pulse Duration
(T_J Initial = 25°C)

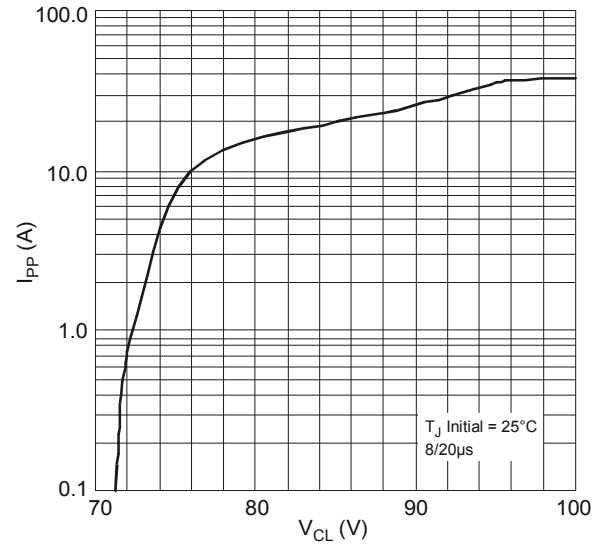


Figure 4 Clamping Voltage vs. Peak Pulse Current
(Exponential Waveform, Maximum Values)

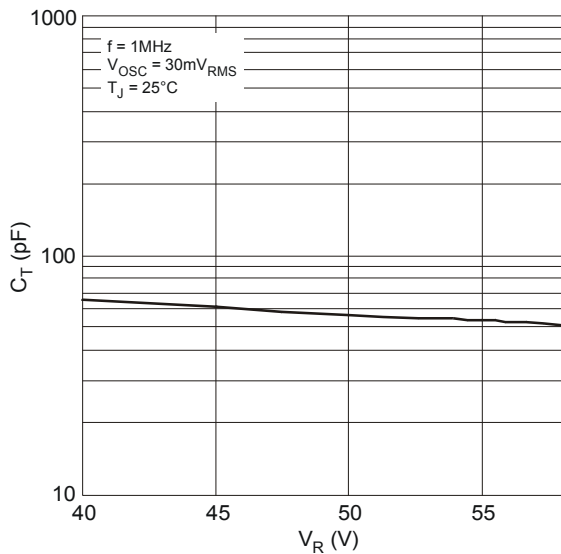


Figure 5 Capacitance vs. Voltage (typical values)

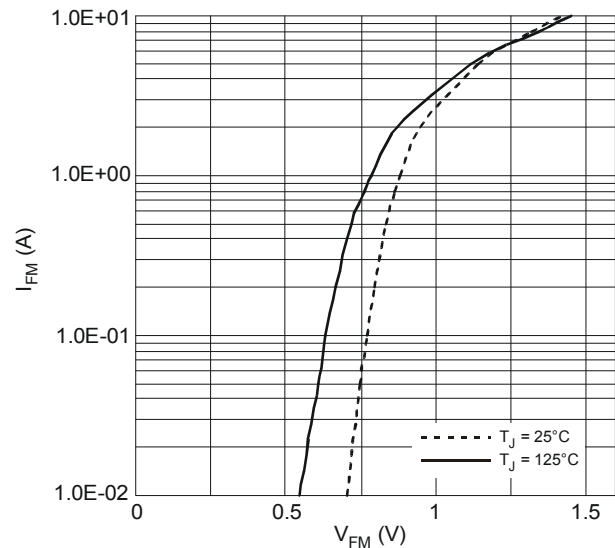


Figure 6 Peak Forward Voltage Drop vs.
Peak Forward Current (typical values)

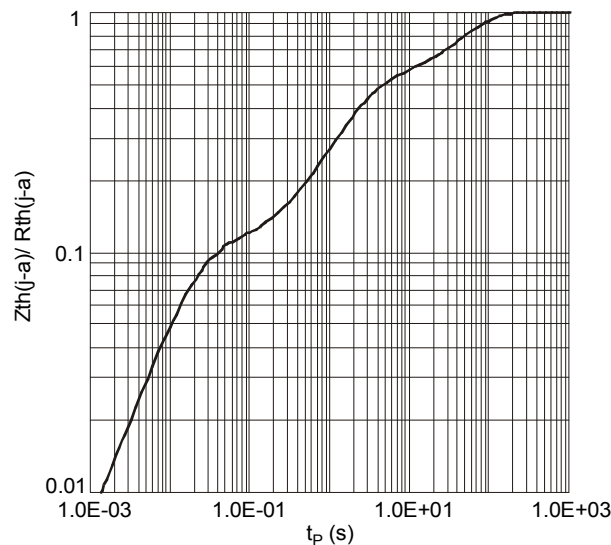


Figure 7 Relative Variation of Thermal Impedance
Junction Ambient vs. Pulse Duration

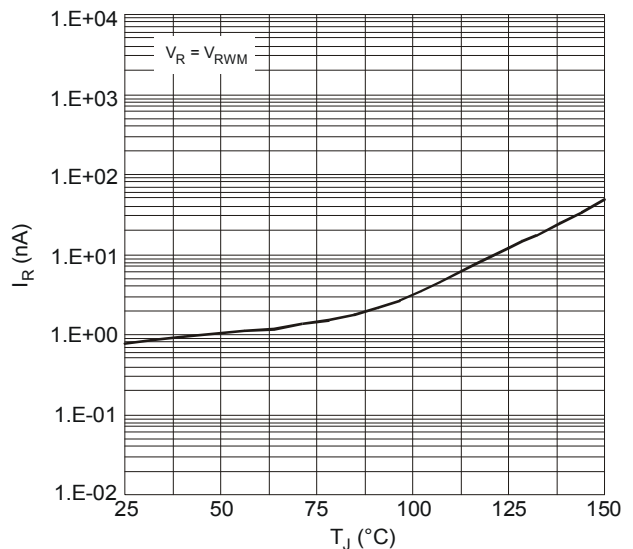
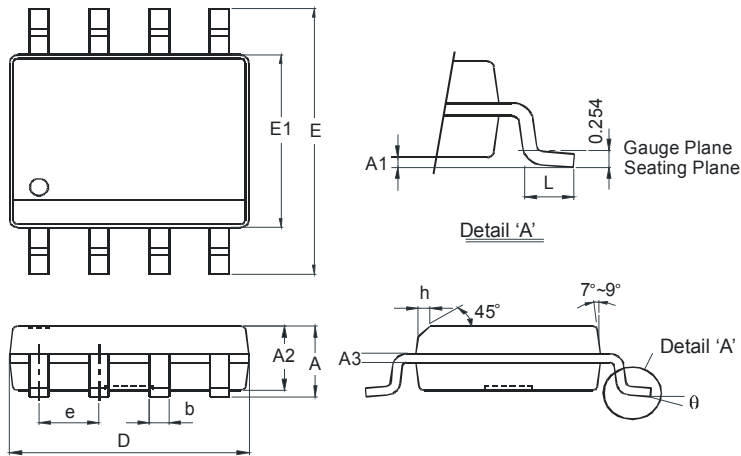


Figure 8 Leakage Current vs. Junction Temperature
(typical values)

Package Outline Dimensions

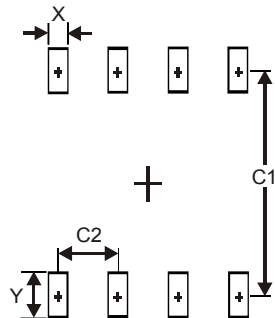
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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